Amendments to the Specification:

Please replace the paragraph beginning on **page 1, at line 21**, with the following amended paragraph:

Cables and connectors must be allowed to deliver their signals unimpeded. Unfortunately, cables and connectors for connecting electronic devices and specialized cabling that ~~incorporates~~ incorporate passive and active electrical devices in a flexible substrate material (e.g., flexible circuits) are both receptors and emitters of EMI radiation. Impingement of EMI can disrupt the functionality of the cable and connectors, and in some cases may cause electronic failure of the cables. With microprocessor speeds continuing to increase, the creation of EMI is a substantial concern to designers, manufacturers, and owners of electronic equipment.

Please replace the paragraph beginning on **page 4, at line 10**, with the following amended paragraph:

In some embodiments, the cable body and/or thermoform can be metallized over two surfaces. In addition to increasing attenuation of the impinging radiation by 10 dB to 20 dB, the second metallized layer provides insurance against the creation of a slot antenna. Thus, if one of the ~~layer~~ layers is scratched or otherwise damaged, the second metallized layer can still block the emission or impingement of the radiation.

Please replace the paragraph beginning on **page 6, at line 30**, with the following amended paragraph:

In some embodiments, the thermoform conductive connector will be detachable from the metallized layer on the cable body. Thus, the conductive connector may be a one piece ("clamshell shape") or a two piece assembly that can be attached (and detached) around the cable body. In general, the conductive connector will have mating surfaces to ~~coupled~~ couple the connector about the cable. For example, mating surfaces of the split connector may have a tongue and groove assembly that can create a tight fitting snap fit. A more complete description of foldable (i.e., split) thermoformable housings can be found in U.S. Patent No. 5,811,050 to

Gabower et al., the complete disclosure of which is incorporated herein by reference for all purposes.

Please replace the paragraph beginning on **page 8, at line 22**, with the following amended paragraph:

Figure 5 illustrates an embodiment of the thermoform connector assembly that uses overlapping or tongue and groove surfaces to connect the connector bodies 32, 33. A first side 40 of the connector assembly can have a bump and a second side 42 of the connector body can have a corresponding dip. The second connector body 33 of the connector body 33 can have a similar pattern so as to provide a combination that connects the two portions 32, 33 snugly around the connector pin assembly 34. It should be appreciated however, that various other conventional or proprietary methods can be used to secure the first end 40 to the second end 42 of the connector. For example, the ends can be attached with [[a]] clamps, spring clips, a conductive adhesive, a conductive gasket, interference fit, laser welded, or the like. Such configurations can allow disassembly of the connector a number of times without damaging the EMI/RFI shielding capability of the cable assembly.

Please replace the paragraph beginning on **page 9, at line 14**, with the following amended paragraph:

Figure 9 is a cross-sectional view of an exemplary electrical connection of the metallized surface 26 of the cable body with a metallized internal surface 37 of a metallized thermoform connector 30 (vacuum metallized with aluminum, copper, or other conductive materials). In some arrangements, small bumps 46 can be positioned along the inner surface 44 of the connector and/or the metallized surface 26 of the flexible cable 22 to create a pressure contact between the cable body 20 and the connector 30 to maintain the positions of the cable relative to the connector during assembly. The spacing of the bumps will depend on the frequencies of the EMI/RF emissions. Thus for higher frequencies, a closer spacing of the bumps is required to block the EMI/RF emissions. The height of the bumps ~~are~~ is also designed in accordance with frequency considerations. Similarly, for high frequencies, the height of the bumps must be reduced so as to be able to block the high frequency emissions. Any gap 49 in

the connector and metallized layer should be no larger than one-half a wavelength of the emitted EMI/RFI radiation.